



500.40053X00

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant(s): S. ISHIHARA, et al  
Serial No.: 09/830,127  
Filed: April 24, 2001  
For: MULTILAYER ELECTRONIC PART, ITS MANUFACTURING  
METHOD, TWO-DimensionALLY ARRAYED ELEMENT  
PACKAGING STRUCTURE, AND ITS MANUFACTURING  
METHOD  
Group: 2822  
Examiner: R. Potter

**AMENDMENT**

Mail Stop - Fee Amendment  
Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

January 16, 2004

Sir:

In response to the Office Action October 16, 2003, the following amendments and remarks are respectfully submitted in connection with the above-identified application, as listed below and as set forth on the following pages:

Amendment of the Claims; and

Remarks are included following the amendments.

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